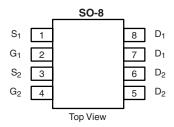


## N- and P-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY							
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
N-Channel	40	$0.0355$ at $V_{GS} = 10 \text{ V}$	6.8	5.3			
	40	$0.0425$ at $V_{GS} = 4.5 \text{ V}$	6.2	5.5			
P-Channel	nnel - 40	$0.045$ at $V_{GS} = -10 \text{ V}$	- 5.8	11.8			
1 -Onaillei		$0.062$ at $V_{GS} = -4.5$ V	- 5.0	11.0			



Ordering Information: Si4599DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

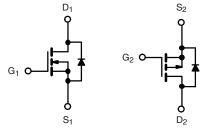
#### **FEATURES**

- Halogen-free
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested 100 % UIS Tested

COMPLIANT

#### **APPLICATIONS**

- Backlight Inverter for LCD Display
- Full Bridge Converter



N-Channel MOSFET

P-Channel MOSFET

Parameter	Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage	V <sub>DS</sub>	40	- 40	V	
Gate-Source Voltage	V <sub>GS</sub>	±	7 '		
	T <sub>C</sub> = 25 °C		6.8	- 5.8	
Continuous Drain Current /T 150 °C\	T <sub>C</sub> = 70 °C		5.4	- 4.7	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	5.6 <sup>b, c</sup>	- 4.7 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		4.4 <sup>b, c</sup>	- 3.7 <sup>b, c</sup>	1
Pulsed Drain Current	I <sub>DM</sub>	20	- 20	Α	
Course Ducie Courset Diede Courset	T <sub>C</sub> = 25 °C		2.5	- 2.5	
Source-Drain Current Diode Current	T <sub>A</sub> = 25 °C	- I <sub>S</sub> -	1.6 <sup>b, c</sup>	- 1.6 <sup>b, c</sup>	
Pulsed Source-Drain Current	I <sub>SM</sub>	20	- 20		
Single Pulse Avalanche Current		I <sub>AS</sub>	7	- 10	
Single Pulse Avalanche Energy	L = 0 1 mH	E <sub>AS</sub>	2.45	5	mJ
	T <sub>C</sub> = 25 °C		3.0	3.1	
Manipular Davier Discipation	T <sub>C</sub> = 70 °C		1.9	2	10/
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.0 <sup>b, c</sup>	2.0 <sup>b, c</sup>	W
	T <sub>A</sub> = 70 °C		1.25 <sup>b, c</sup>	1.25 <sup>b, c</sup>	
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 t	°C		

THERMAL RESISTANCE RATINGS								
		N-Channel P-Ch			annel			
Parameter			Тур.	Max.	Тур.	Max.	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup> t ≤ 10 s		R <sub>thJA</sub>	54	64	49	62.5	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	33	42	30	40	O/ <b>VV</b>	

- a. Based on  $T_C$  = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 120 °C/W.

## Si4599DY Vishay Siliconix



Parameter	Symbol	Test Conditions		Min.	Typ. <sup>a</sup>	Max.	Unit
Static	,		l				l
Durin Course Burnhalous Valle	V	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	N-Ch	40			.,
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$	P-Ch	- 40			V
	A) / /T	I <sub>D</sub> = 250 μA	N-Ch		44		
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μA	P-Ch		- 42		
V Tanana ana hana O a Waisan		I <sub>D</sub> = 250 μA	N-Ch		- 5.5		mV/°
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	II <sub>D</sub> = - 250 μA	P-Ch		4.6		
	.,	$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	1.4		3.0	1
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	- 1.2		- 2.5	V
Oaks Bartal aslance		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	N-Ch			100	4
Gate-Body Leakage	I <sub>GSS</sub>		P-Ch			- 100	nA
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch			1	μΑ
Zava Cata Valtaga Dvain Current		V <sub>DS</sub> = - 40 V, V <sub>GS</sub> = 0 V	P-Ch			- 1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	N-Ch			10	
		$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	P-Ch			- 10	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	10			А
		$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	P-Ch	- 10			
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	N-Ch		0.0295	0.0355	Ω
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A	P-Ch		0.037	0.045	
		$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$	N-Ch		0.0355	0.0425	
		$V_{GS} = -4.5 \text{ V}, I_D = -4 \text{ A}$	P-Ch		0.050	0.062	
	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 5 \text{ A}$	N-Ch		22		_
Forward Transconductance <sup>b</sup>		V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 5 A	P-Ch		14		S
Dynamic <sup>a</sup>							
•			N-Ch		640		
Input Capacitance	C <sub>iss</sub>	N-Channel	P-Ch		970		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch		73		pF
- Carpar Capacitarios	Oss	P-Channel	P-Ch		120		
Reverse Transfer Capacitance	$C_{rss}$	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch		41		
·		V 00 V V 10 V I 5 A	P-Ch N-Ch		95		
		$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$			11.7	20	
Total Gate Charge	$Q_{g}$	$V_{DS} = -20 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -5 \text{ A}$	P-Ch		25	38	
-		N-Channel	N-Ch		5.3	9	_
		$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V} I_D = 5 \text{ A}$	P-Ch N-Ch		11.8	18	nC
Gate-Source Charge	$Q_{gs}$		P-Ch		3.0	-	ł
	Q <sub>gd</sub>	P-Channel $V_{DS} = -20 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$	N-Ch		1.7		
Gate-Drain Charge		v <sub>DS</sub> = -20 v, v <sub>GS</sub> = -4.3 v, I <sub>D</sub> = -5 A	P-Ch		5.2		
0.1.5		f = 1 MHz	N-Ch	0.5	2.2	4.5	_
Gate Resistance	$R_g$		P-Ch	1.0	5.5	11	Ω





<b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C,				N.42	T a	Mari	11
Parameter	Symbol Test Conditions			Min.	Typ. <sup>a</sup>	Max.	Unit
Dynamic <sup>a</sup>							
Turn-On Delay Time	t <sub>d(on)</sub>	N-Channel	N-Ch		7	14	
	u(on)	$V_{DD} = 20 \text{ V, } R_L = 4 \Omega$	P-Ch		7	14	_
Rise Time	t <sub>r</sub>	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_q = 1 \Omega$	N-Ch		10	20	
		- GEN 7 g	P-Ch		12	24	
Turn-Off Delay Time	$t_{d(off)}$	P-Channel	N-Ch		15	30	
·	- (- /	$V_{DD} = -20 \text{ V}, R_L = 4 \Omega$	P-Ch		30	60	ns
Fall Time	t <sub>f</sub>	$I_D \cong$ - 5 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$	N-Ch		9	18	
			P-Ch		9	18	
Turn-On Delay Time	$t_{d(on)}$	N-Channel	N-Ch		16	30	
	. (. ,	$V_{DD} = 20 \text{ V}, R_L = 4 \Omega$	P-Ch N-Ch		44	80	  - 
Rise Time	t <sub>r</sub>	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_q = 1 \Omega$	P-Ch		17	30	
	t <sub>d/off)</sub> P-Channel	N-Ch		33 16	50 30	4	
Turn-Off Delay Time			P-Ch		28	60	
	t <sub>f</sub>	$V_{DD} = -20 \text{ V}, R_L = 4 \Omega$	N-Ch		10	20	
Fall Time		$I_D \cong$ - 5 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$	P-Ch		13	25	
Drain-Source Body Diode Characterist	ice		1 -011		1 10	25	
Brain Course Body Brode Characterist			N-Ch		1	2.5	1
Continuous Source-Drain Diode Current		T <sub>C</sub> = 25 °C	P-Ch			- 2.5	-
			N-Ch			20	Α
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>		P-Ch			- 20	
		I <sub>S</sub> = 1.6 A	N-Ch		0.78	1.2	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 1.6 A	P-Ch		- 0.76	- 1.2	V
	t <sub>rr</sub>	3 -	N-Ch		19	30	
Body Diode Reverse Recovery Time			P-Ch		26	50	ns
	Q <sub>rr</sub>	N-Channel	N-Ch		14	25	_
Body Diode Reverse Recovery Charg		$I_F = 2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$	P-Ch		18.5	35	nC
		- P-Channel	N-Ch		13		
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -2 \text{ A}$ , dl/dt = -100 A/ $\mu$ s, $T_J = 25 ^{\circ}\text{C}$	P-Ch		12.5		1
Deverage December Dies Time	t <sub>b</sub>	, and its rape, rg <b>20 0</b>	N-Ch		6		ns
Reverse Recovery Rise Time			P-Ch		13.5		1

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Guaranteed by design, not subject to production testing.

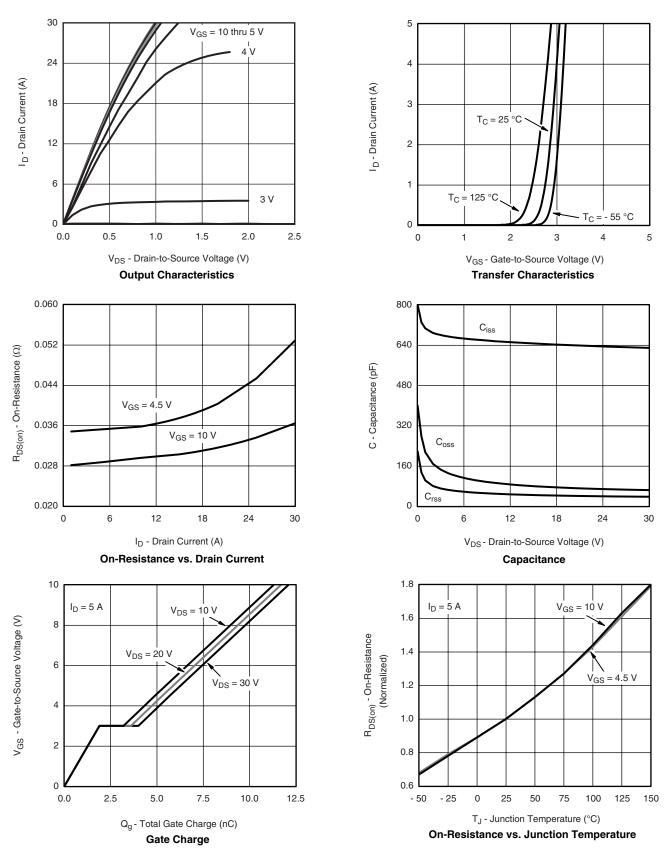
b. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

### Si4599DY

## Vishay Siliconix

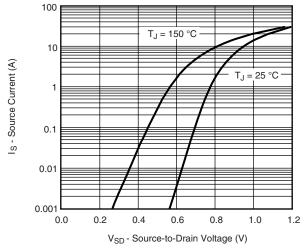


#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

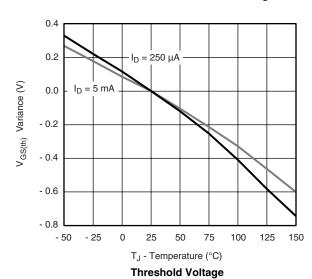




#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

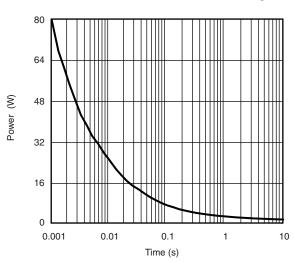


#### Source-Drain Diode Forward Voltage

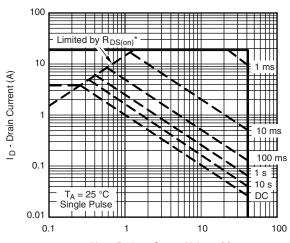


0.20  $I_D = 5 \text{ A}$   $I_D = 6 \text{ A}$   $I_D = 6$ 

 $\label{eq:VGS} V_{GS} \mbox{ - Gate-to-Source Voltage (V)} \\$  On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

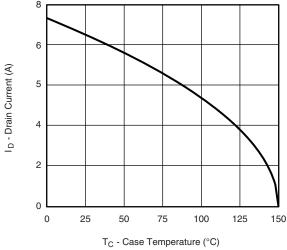


 $V_{DS} \text{ - Drain-to-Source Voltage (V)} \\ ^*V_{GS} > \text{minimum } V_{GS} \text{ at which } r_{DS(on)} \text{ is specified}$ 

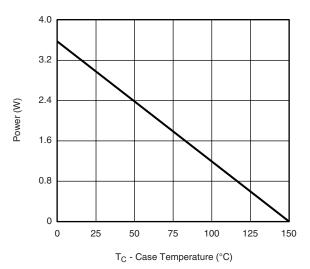
Safe Operating Area, Junction-to-Ambient

# VISHAY.

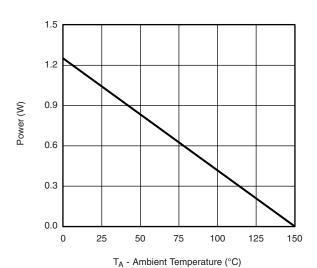
#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating\*





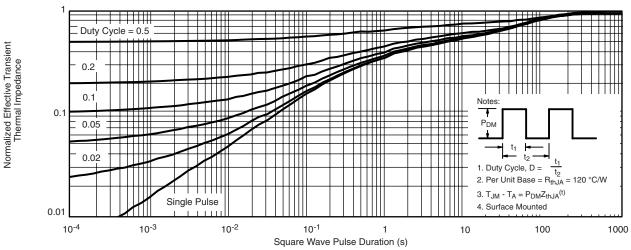


Power Derating, Junction-to-Ambient

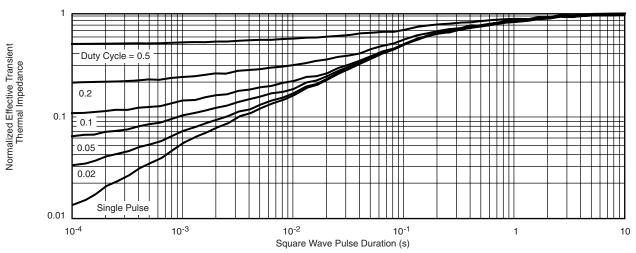
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



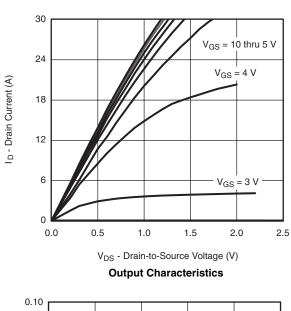
Normalized Thermal Transient Impedance, Junction-to-Ambient

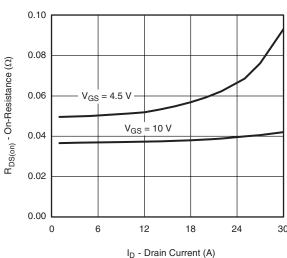


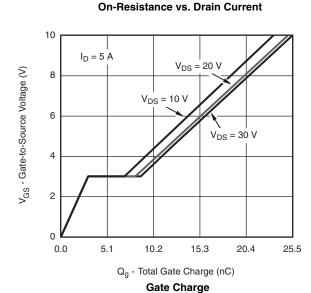
Normalized Thermal Transient Impedance, Junction-to-Foot

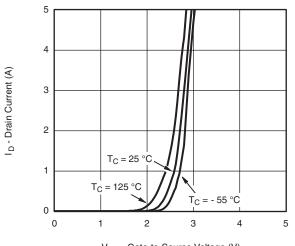
# VISHAY

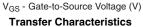
#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

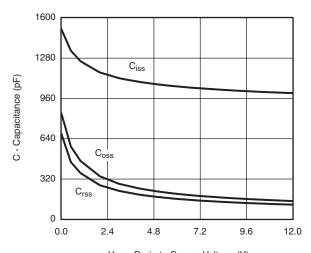






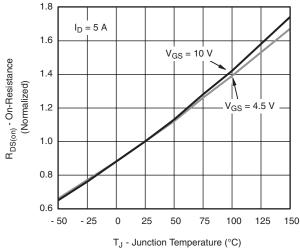






 $V_{\mbox{\scriptsize DS}}$  - Drain-to-Source Voltage (V)

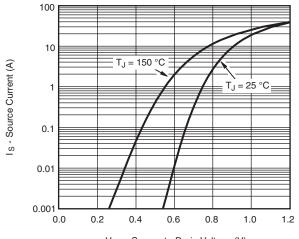
## Capacitance



On-Resistance vs. Junction Temperature

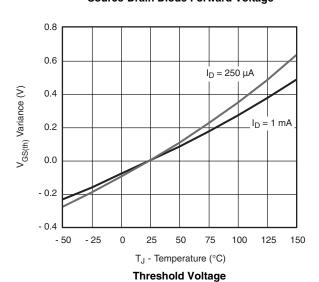


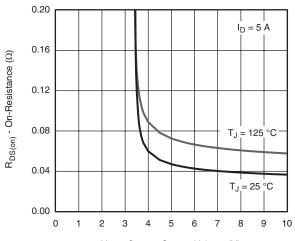
#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



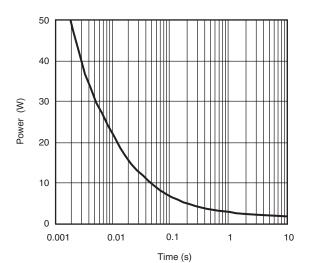
 $V_{\mbox{SD}}$  - Source-to-Drain Voltage (V)

#### **Source-Drain Diode Forward Voltage**

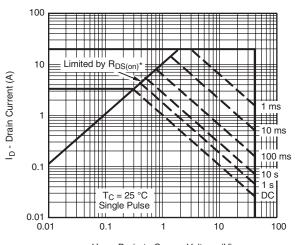




 $\label{eq:VGS} V_{GS} \mbox{ - Gate-to-Source Voltage (V)} \\$  On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



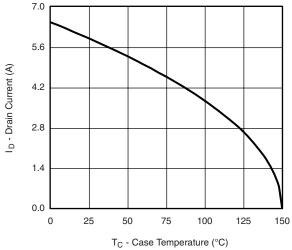
 $V_{\mbox{\footnotesize DS}}$  - Drain-to-Source Voltage (V)

Safe Operating Area, Junction-to-Ambient

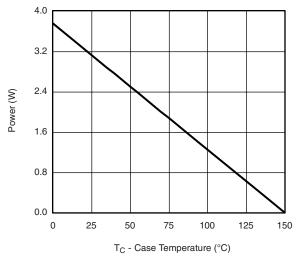
 $<sup>^{\</sup>star}$   $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

# VISHAY.

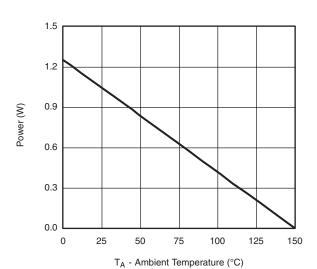
#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating\*





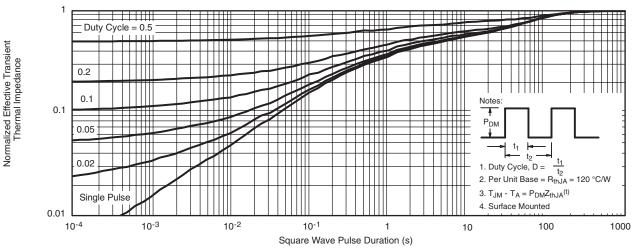


Power Derating, Junction-to-Ambient

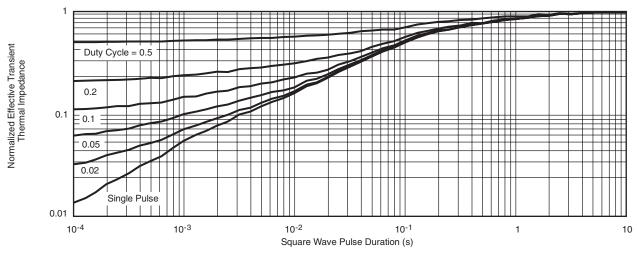
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	1.27 BSC		) BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



#### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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Vishay

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